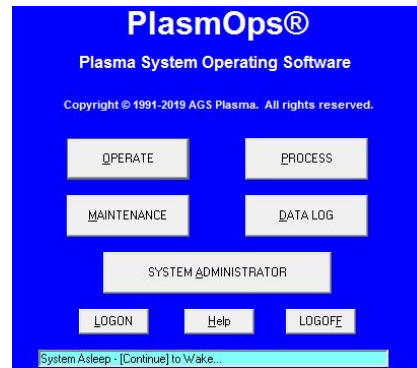




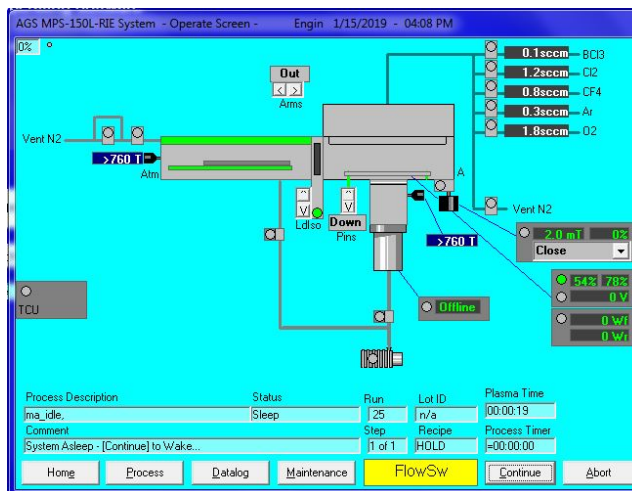
AGS Reactive Ion Etcher (Metal) SOP

1. Log onto the PlasmOps program with username “guest” and password “guest”

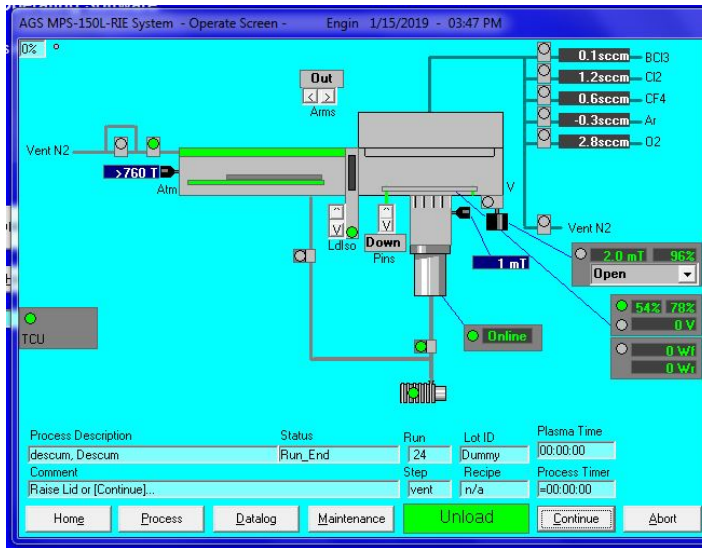


2. Click “operate” at the home page. Ready to load your sample in the loadlock.

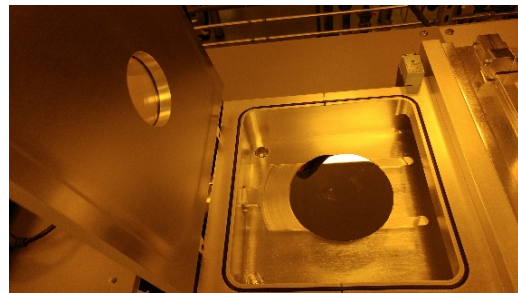
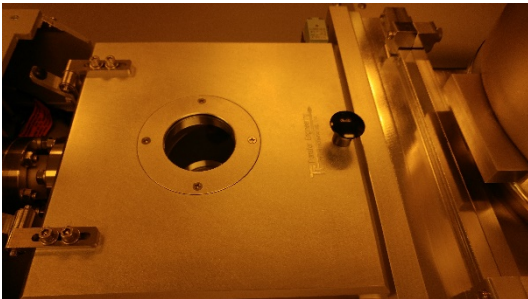
3. To turn on the Chiller first by clicking . It will turn green. Clear the “Flow Sw” by double click on it. Then turn on the roughing pump by clicking . It will turn green. Then click “Continue”.



4. Once “unload” is shown, ready for loading sample.



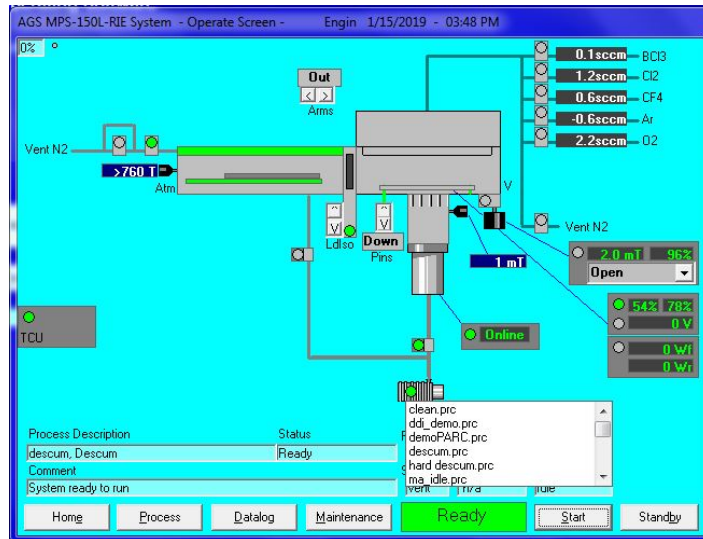
3. Open loadlock and tape small sample onto the wafer. For wafer samples, remove the loading wafer and directly put your wafer sample onto the transfer arm.



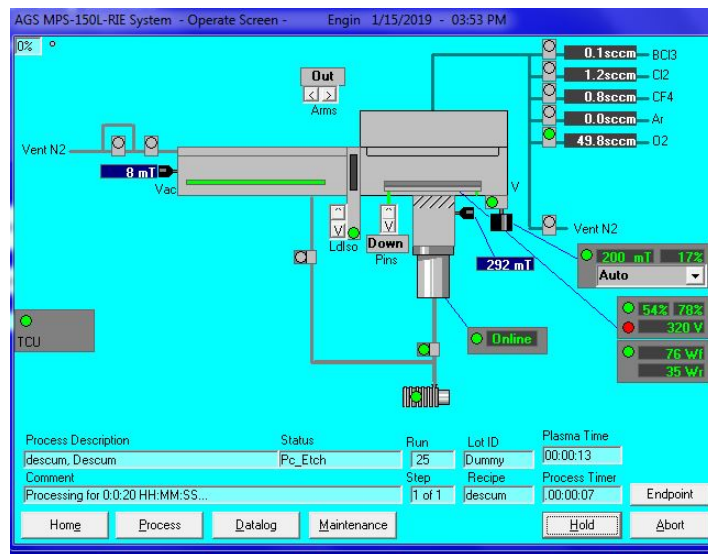
4. Turn on the power supply on the front panel.



5. The system shows “Ready” once chiller and pump are on line. Recipes can be chosen through a recipe window. Click the recipe you want to run. Then click start to run.



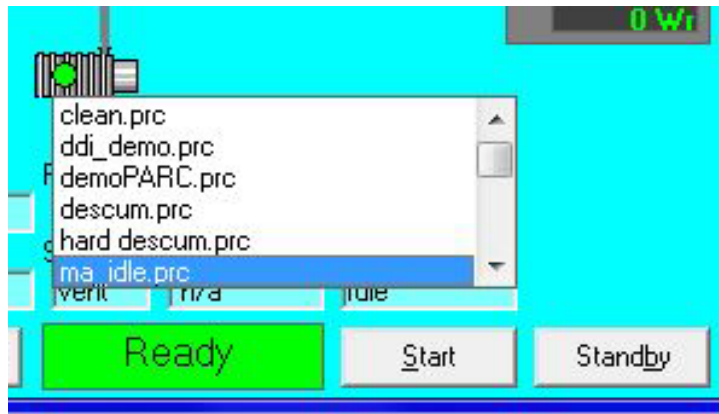
6. The system will run the recipe automatically. It will show the process steps under “comment” Power data and plasmas indication will be shown when the etching process step starts



7. Once the recipe is over. The chamber should be vented and ready for unload. Unload your sample and close the cover.

8. Shutting down the system:

1. Run the “ma_idle.prc” process. The system will automatically shut off everything through the process.



2. Click “Home” to go back to home page and click “LOG OFF”

3. Turn off the RF power supply from the front panel. LEAVE main power panel ON!

4. Log off FOM.